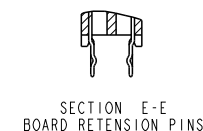
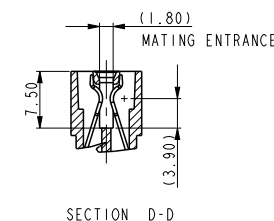
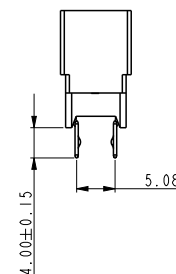
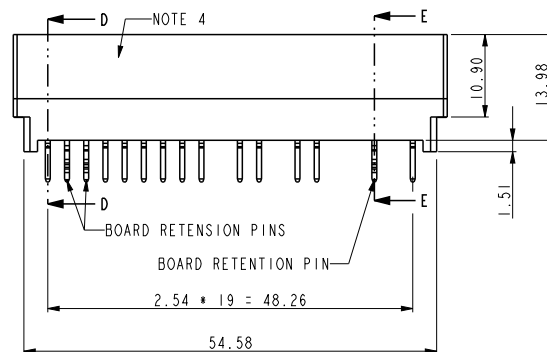
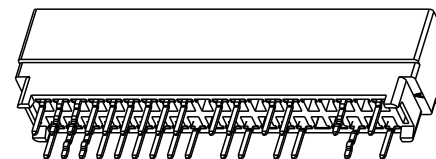
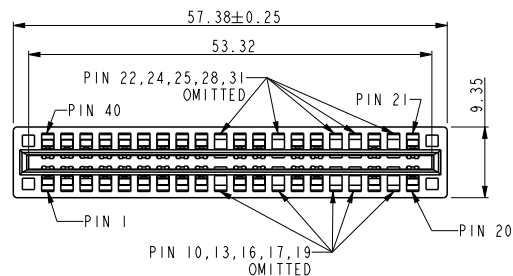


PRODUCT NO  
10046971-043LF

REV.	ECN	REV'D BY	DATE
A	---	JW	2013-11-27



- NOTE:
- MATERIAL:  
HOUSING: HIGH TEMPERATURE THERMOPLASTIC,  
UL 94 V-0 FLAME RETARDANT.  
TERMINAL: HIGH CONDUCTIVITY COPPER ALLOY.  
PLATING SPEC AS BELOW:  
Ni 50u" UNDER PLATED.  
Au 30u" OVER CONTACT AREA (ONE SIDE)  
MATTE PURE TIN 120u" OVER SOLDERING AREA.
  - PACKING SPEC. GS-14-937
  - PRODUCT SPEC. GS-12-338.
  - MANUFACTURER'S NAME, P/N AND DATE CODE  
TO APPEAR ON THIS SURFACE AS PER GS-24-007.

- PART NUMBER 10046971-043LF MEETS EUROPEAN UNION DIRECTIVE AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A CIRCUIT BOARD.
- THE PINS 10, 13, 16, 17, 19, 22, 24, 25, 28, 31 ARE OMITTED.

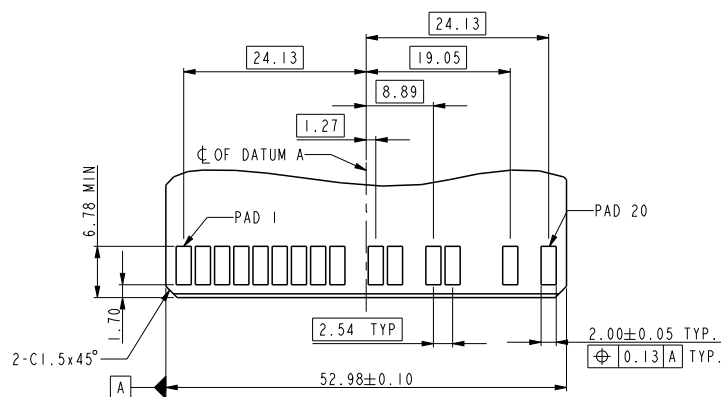
spec ref	*	dr	Julia Wang	2013/11/25	projection	MM	size	A4	scale	1.000
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Julia Wang	2013/12/06			ecn no	-	rel level	Released
ISO 406		chr	-	-						
ISO 1101		appr	Pei-Ming Zheng	2013/12/06	product family	Power Edge Card				
surface	linear				title	VERTICAL TYPE	dwg no	10046971-043	rev	A
ISO 1302	angular					2X20P(10P OMITTED)				
					cat. no.	*	Product - Customer Drw	sheet 1 of 2		

PrintE File - REV C - 2009-06-09

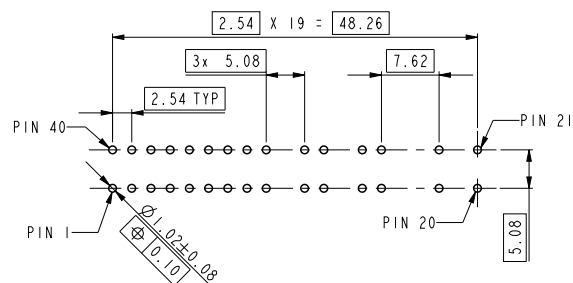
PDS: Rev :A

STATUS:Released

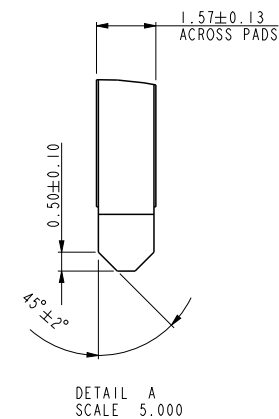
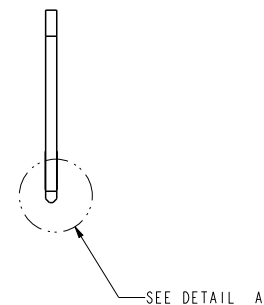
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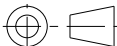




RECOMMENDED MATING BOARD



RECOMMENDED PC BOARD LAYOUT  
AND THE THICKNESS IS 3.18mm



dr	Julia Wang	2013/11/25	<div>projection</div> <div></div>	<div>MM</div> <div></div>	size	A4	scale	1.000			
eng	Julia Wang	2013/12/06			ecn no	-					
chr	-	-									
appr	Pei-Ming Zheng	2013/12/06	product family		Power Edge Card		rel level		Released		
		title			VERTICAL TYPE 2X20P(10P OMITTED)		dwg no		10046971-043	rev	A
www.fci.com		cat. no.		*	Product - Customer Drw				sheet 2 of 2		